

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

OKU et al

Serial No.:

Filed: July 13, 2001

For: FILM FORMING METHOD, SEMICONDUCTOR DEVICE  
AND SEMICONDUCTOR DEVICE MANUFACTURING METHOD

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

Please amend the captioned application as follows:

IN THE SPECIFICATION:

Please insert the following new paragraph after the third paragraph at page 9 of the specification:

—Fig. 16 is a sectional view showing a semiconductor device manufacturing method according to the other embodiment of the present invention.—

Respectfully submitted,

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Dated: July 13, 2001  
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FIG. 15

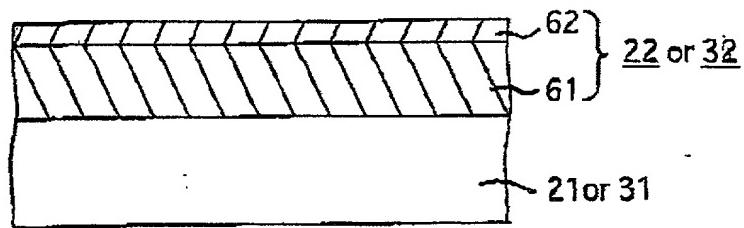
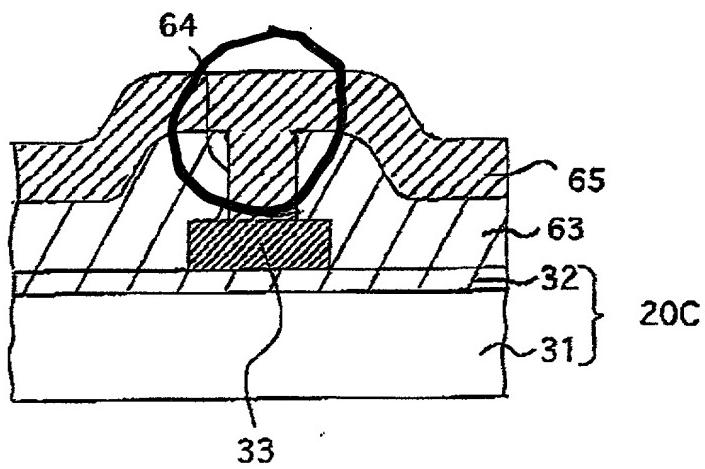
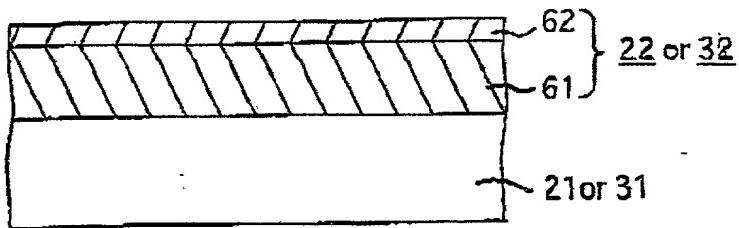


FIG. 16



**FIG. 15**



**FIG. 16**

